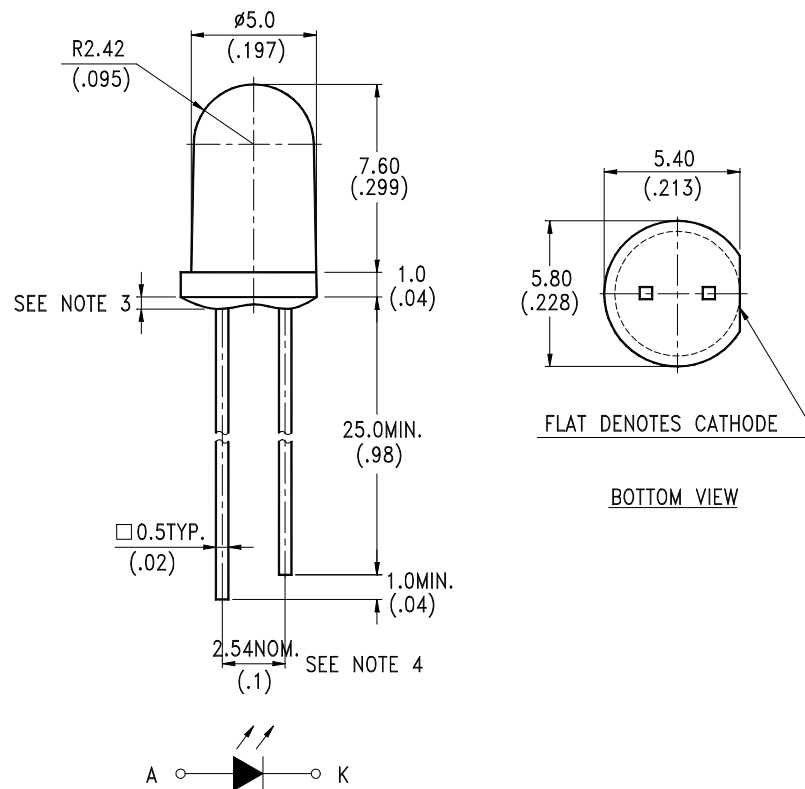


FEATURES

- * SPECIAL FOR HIGH CURRENT AND LOW FORWARD VOLTAGE
- * HIGH POWER
- * AVAILABLE FOR PULSE OPERATING
- * WIDE VIEWING ANGLE
- * LIGHT BLUE TRANSPARENT COLOR PACKAGE
- * TIN DIPPING LEADS

PACKAGE DIMENSIONS



NOTES:

1. All dimensions are in millimeters (inches).
2. Tolerance is $\pm 0.25\text{mm}(.010")$ unless otherwise noted.
3. Protruded resin under flange is 1.5mm(.059") max.
4. Lead spacing is measured where the leads emerge from the package.
5. Specifications are subject to change without notice.

ABSOLUTE MAXIMUM RATINGS AT TA=25°C

PARAMETER	MAXIMUM RATING	UNIT
Power Dissipation	150	mW
Peak Forward Current (300pps, 10 μ s pulse)	2	A
Continuous Forward Current	100	mA
Reverse Voltage	5	V
Operating Temperature Range	-40°C to + 85°C	
Storage Temperature Range	-55°C to + 100°C	
Lead Soldering Temperature [1.6mm(.063") From Body]	260°C for 5 Seconds	

ELECTRICAL OPTICAL CHARACTERISTICS AT TA=25°C

PARAMETER	SYMBOL	MIN.	TYP.	MAX.	UNIT	TEST CONDITION	Remark
Radiant Intensity	I_E	35	50		mW/sr	$I_F = 100\text{mA}$	
Peak Emission Wavelength	λ_P		940		nm	$I_F = 100\text{mA}$	
Spectral Line Half-Width	$\Delta \lambda$		50		nm	$I_F = 100\text{mA}$	
Forward Voltage	V_F		1.4	1.8	V	$I_F = 100\text{Ma}$	
Reverse Current	I_R			100	μ A	$V_R = 5\text{V}$	
Viewing Angle (See FIG.6)	$2\theta_{1/2}$		60		deg.		

TYPICAL ELECTRICAL / OPTICAL CHARACTERISTICS CURVES

(25°C Ambient Temperature Unless Otherwise Noted)

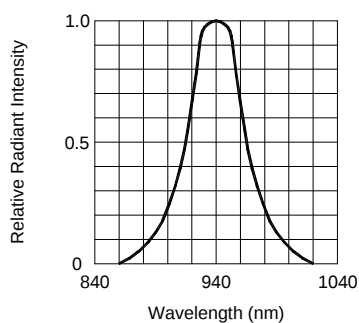


FIG.1 SPECTRAL DISTRIBUTION

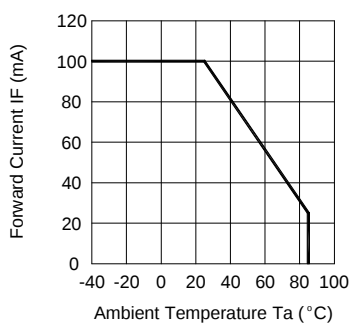


FIG.2 FORWARD CURRENT VS. AMBIENT TEMPERATURE

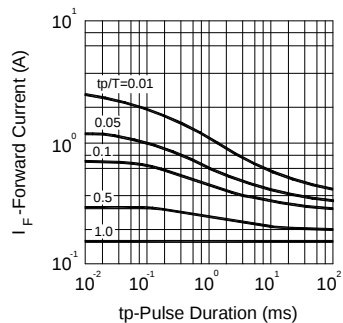


FIG.7 PULSE FORWARD CURRENT VS. PULSE DURATION

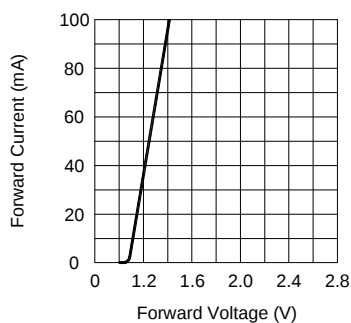


FIG.3 FORWARD CURRENT VS. FORWARD VOLTAGE

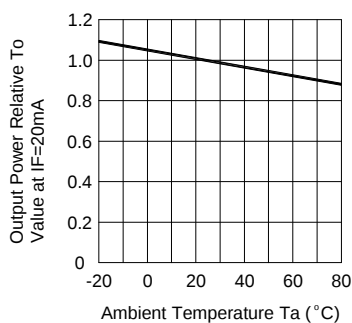


FIG.4 RELATIVE RADIANT INTENSITY VS. AMBIENT TEMPERATURE

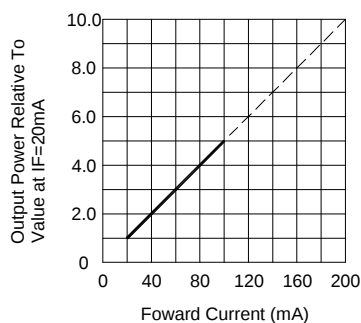


FIG.5 RELATIVE RADIANT INTENSITY VS. FORWARD CURRENT

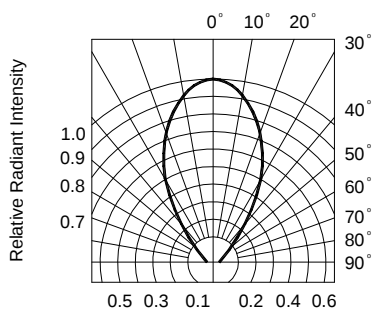


FIG.6 RADIATION DIAGRAM